



SamHop Microelectronics Corp.



STU10N25

STD10N25

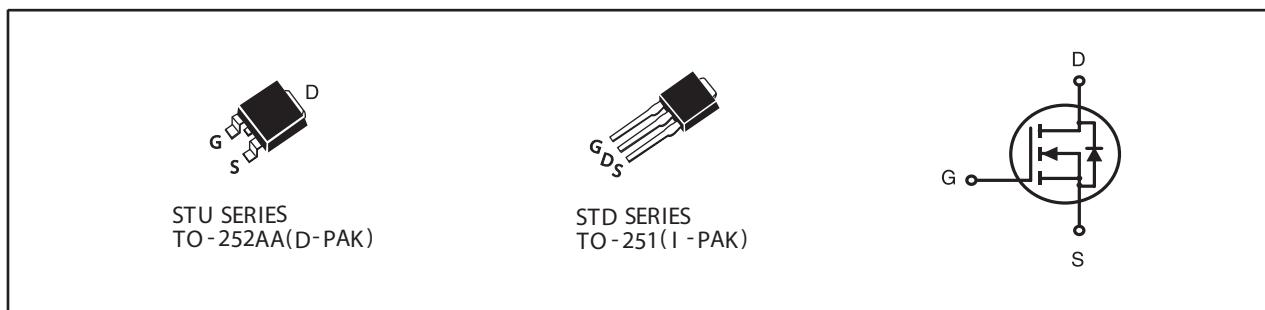
Ver 1.0

N-Channel Logic Level Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
VDSS	ID	RDS(ON) (mΩ) Max
250V	9A	258 @ VGS=10V

FEATURES

- Super high dense cell design for low RDS(ON).
- Rugged and reliable.
- TO-252 and TO-251 Package.



ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Limit	Units
V_{DS}	Drain-Source Voltage	250	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current-Continuous ^{a e}	9	A
	$T_C=25^\circ\text{C}$	9	A
	$T_C=100^\circ\text{C}$	5.7	A
I_{DM}	-Pulsed ^b	25	A
E_{AS}	Single Pulse Avalanche Energy ^d	20	mJ
P_D	Maximum Power Dissipation	42	W
	$T_C=25^\circ\text{C}$	42	W
	$T_C=100^\circ\text{C}$	17	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 to 150	°C

THERMAL CHARACTERISTICS

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	50	°C/W

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ELECTRICAL CHARACTERISTICS (T_c=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =10mA	250			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =200V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±20V , V _{DS} =0V			±100	nA
ON CHARACTERISTICS						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1	2.2	3	V
R _{D(ON)}	Drain-Source On-State Resistance	V _{GS} =10V , I _D =4.5A		206	258	m ohm
g _{FS}	Forward Transconductance	V _{DS} =10V , I _D =4.5A		6.6		S
DYNAMIC CHARACTERISTICS ^c						
C _{ISS}	Input Capacitance	V _{DS} =25V,V _{GS} =0V f=1.0MHz		1610		pF
C _{OSS}	Output Capacitance			78		pF
C _{rss}	Reverse Transfer Capacitance			58		pF
SWITCHING CHARACTERISTICS ^c						
t _{D(ON)}	Turn-On Delay Time	V _{DD} =125V I _D =1A V _{GS} =10V R _{GEN} = 6 ohm		37		ns
t _r	Rise Time			29		ns
t _{D(OFF)}	Turn-Off Delay Time			55		ns
t _f	Fall Time			14		ns
Q _g	Total Gate Charge	V _{DS} =125V,I _D =1A,V _{GS} =10V		22		nC
Q _{gs}	Gate-Source Charge	V _{DS} =125V,I _D =1A, V _{GS} =10V		2.8		nC
Q _{gd}	Gate-Drain Charge			7.4		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
V _{SD}	Diode Forward Voltage	V _{GS} =0V,I _S =4.5A		0.81	1.3	V
Notes						
a.Surface Mounted on FR4 Board,t ≤ 10sec.						
b.Pulse Test:Pulse Width ≤ 300us, Duty Cycle ≤ 2%.						
c.Guaranteed by design, not subject to production testing.						
d.Starting T _J =25°C,L=0.5mH,V _{DD} = 50V.(See Figure13)						
e.Drain current limited by maximum junction temperature.						

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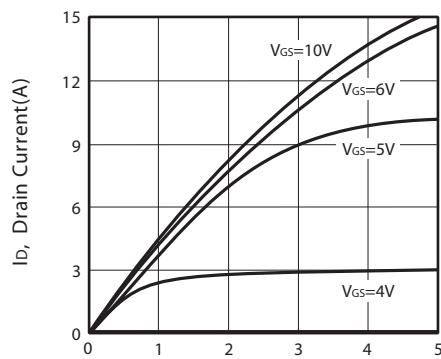


Figure 1. Output Characteristics

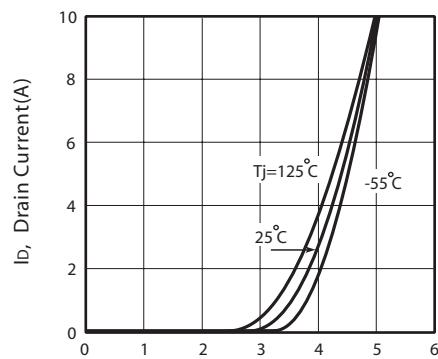


Figure 2. Transfer Characteristics

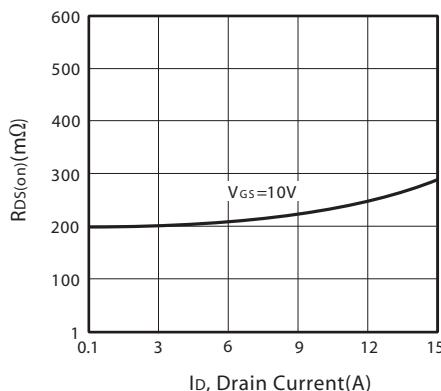


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

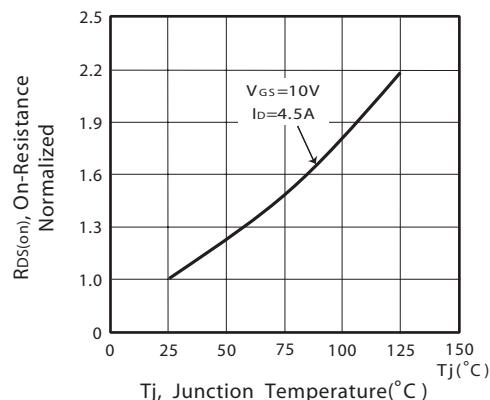


Figure 4. On-Resistance Variation with Drain Current and Temperature

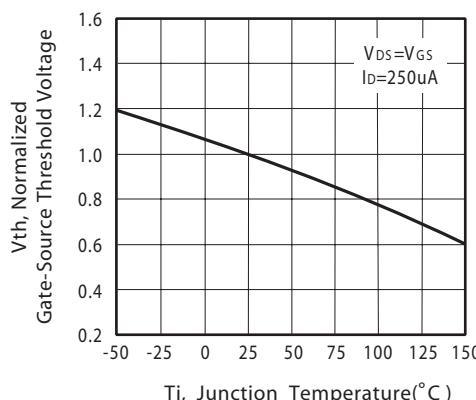


Figure 5. Gate Threshold Variation with Temperature

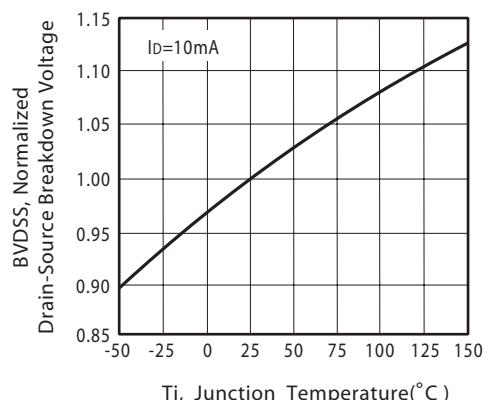
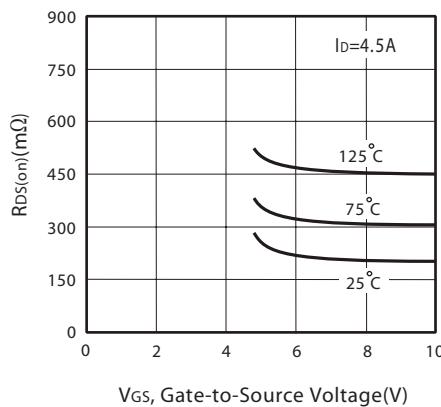


Figure 6. Breakdown Voltage Variation with Temperature

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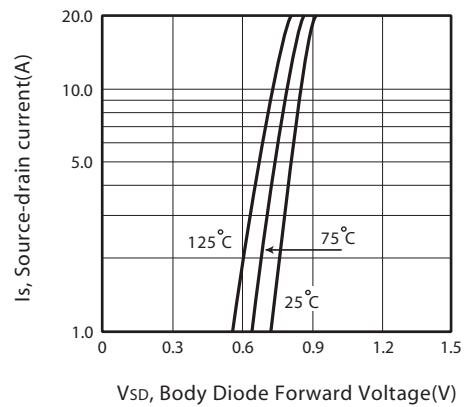
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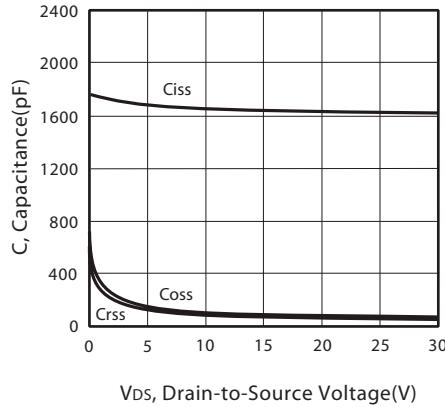
V_{GS}, Gate-to-Source Voltage(V)

Figure 7. On-Resistance vs. Gate-Source Voltage



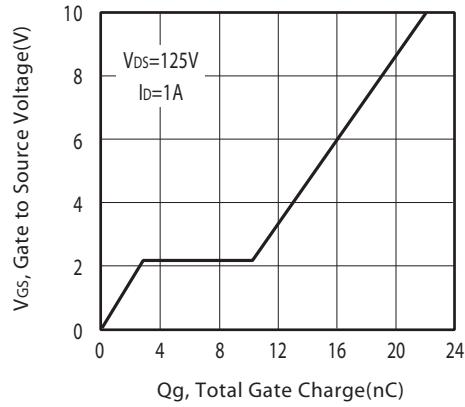
V_{SD} , Body Diode Forward Voltage(V)

Figure 8. Body Diode Forward Voltage Variation with Source Current



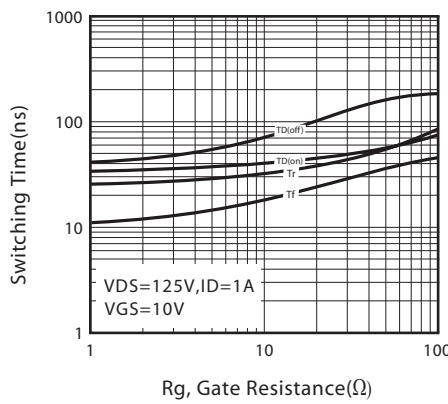
V_{DS} , Drain-to-Source Voltage(V)

Figure 9. Capacitance



Q_g , Total Gate Charge(nC)

Figure 10. Gate Charge



R_g , Gate Resistance(Ω)

Figure 11. switching characteristics

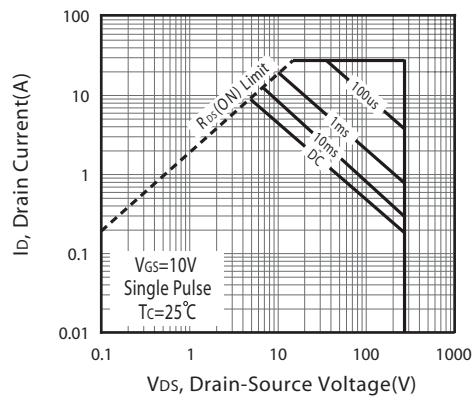


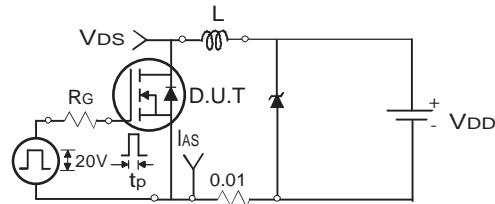
Figure 12. Maximum Safe Operating Area

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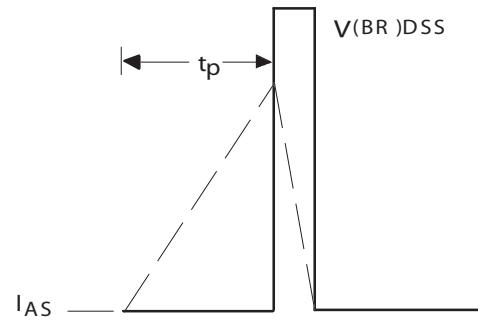
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Uncamped Inductive Test Circuit

Figure 13a.



Unclamped Inductive Waveforms

Figure 13b.

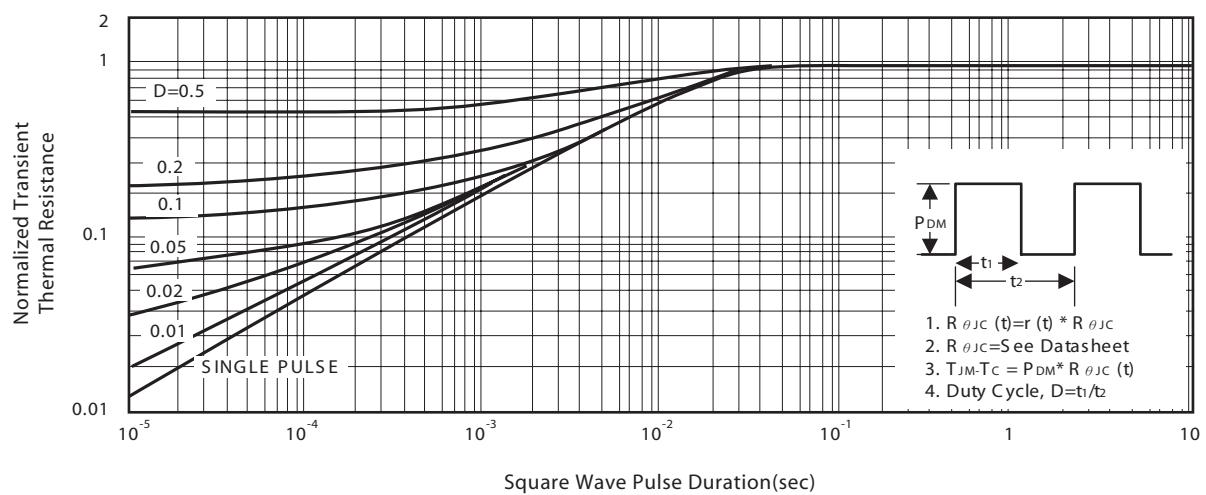
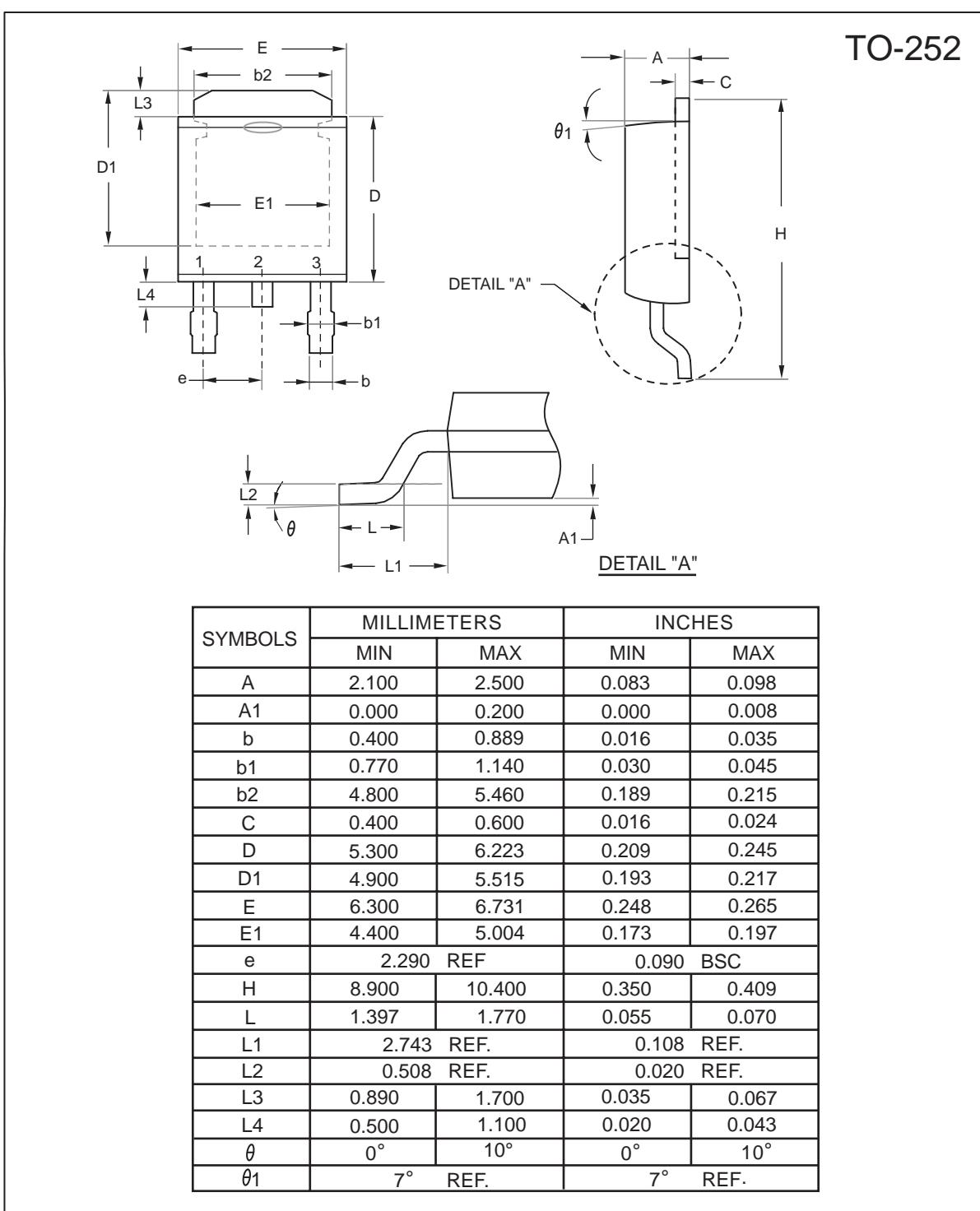


Figure 14. Normalized Thermal Transient Impedance Curve

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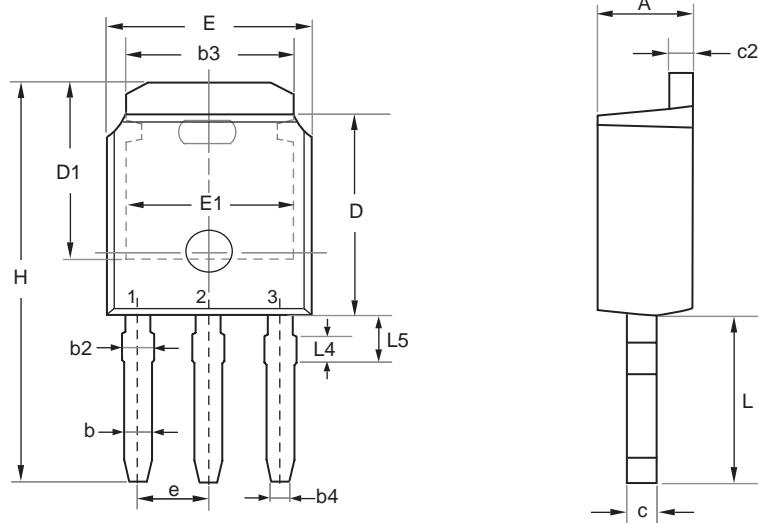
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PACKAGE OUTLINE DIMENSIONS

TO-251



SYMBOL	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
E	6.400	6.731	0.252	0.265
L	3.980	4.280	0.157	0.169
L4	0.698	REF	0.027	REF
L5	0.972	1.226	0.038	0.048
D	6.000	6.223	0.236	0.245
H	11.050	11.450	0.435	0.450
b	0.640	0.880	0.025	0.035
b2	0.770	1.140	0.030	0.045
b3	5.210	5.460	0.205	0.215
b4	0.450	0.550	0.018	0.022
e	2.286	BSC	0.090	BSC
A	2.200	2.380	0.087	0.094
c	0.400	0.600	0.016	0.024
c2	0.400	0.600	0.016	0.024
D1	5.100	---	0.201	---
E1	4.400	---	0.173	---

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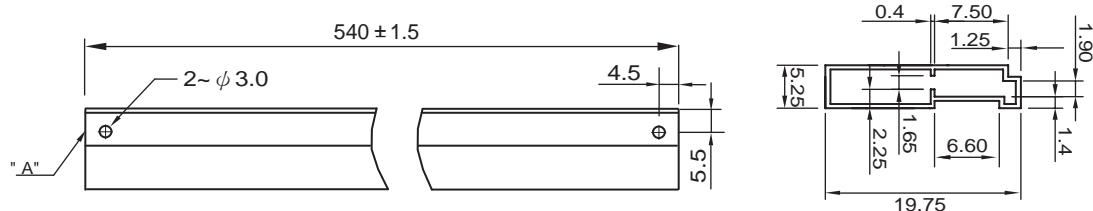
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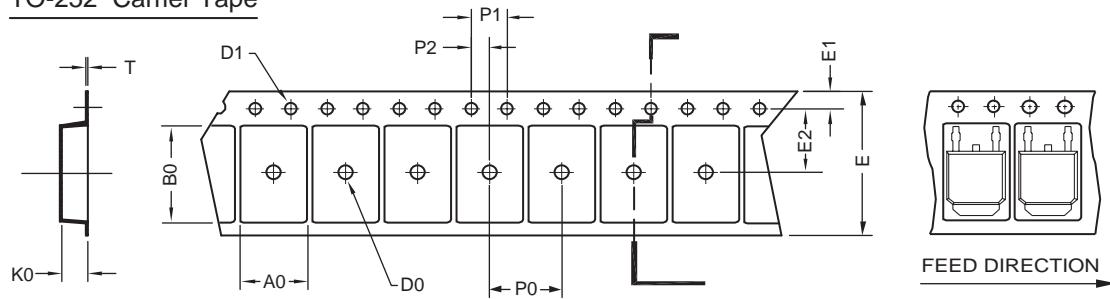
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TO-251 Tube/TO-252 Tape and Reel Data

TO-251 Tube



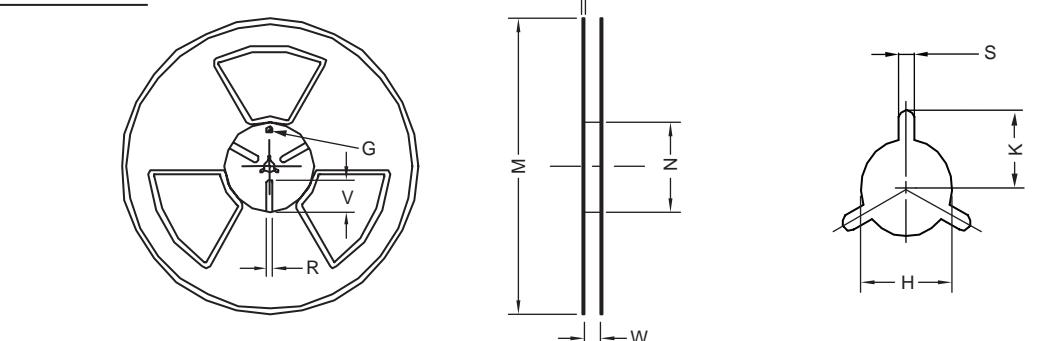
TO-252 Carrier Tape



UNIT:mm

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
TO-252 (16 mm)	6.96 ±0.1	10.49 ±0.1	2.79 ±0.1	ψ 2	ψ 1.5 + 0.1 - 0	16.0 ±0.3	1.75 ±0.1	7.5 ±0.15	8.0 ±0.1	4.0 ±0.1	2.0 ±0.15	0.3 ±0.05

TO-252 Reel



UNIT:mm

TAPE SIZE	REEL SIZE	M	N	W	T	H	K	S	G	R	V
16 mm	ψ 330	ψ 330 ± 0.5	ψ 97 ± 1.0	17.0 + 1.5 - 0	2.2	ψ 13.0 + 0.5 - 0.2	10.6	2.0 ± 0.5	---	---	---

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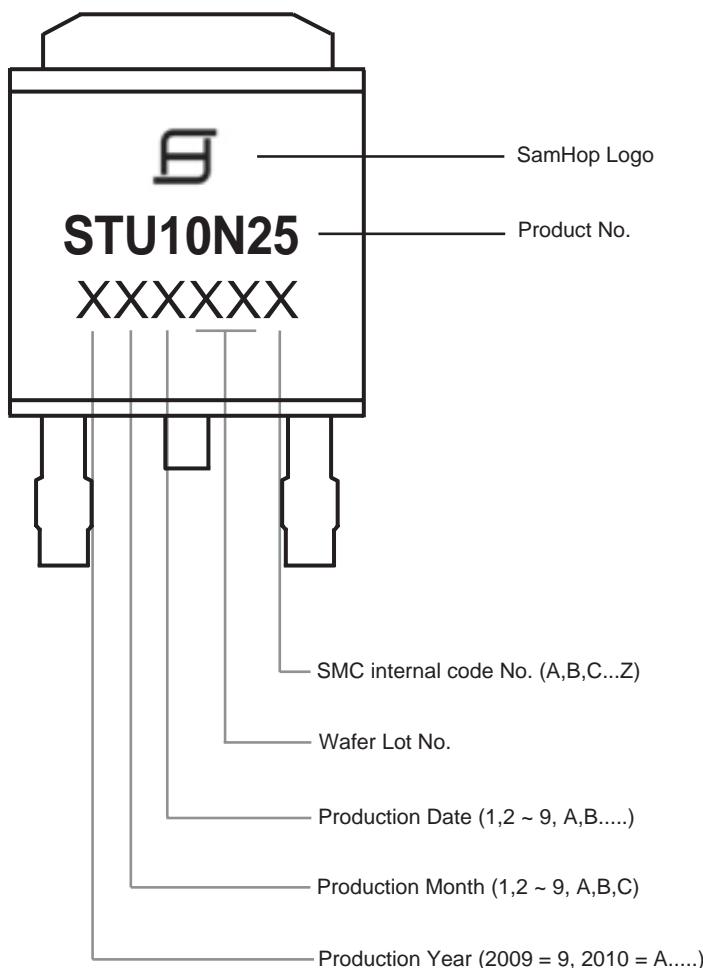
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TOP MARKING DEFINITION

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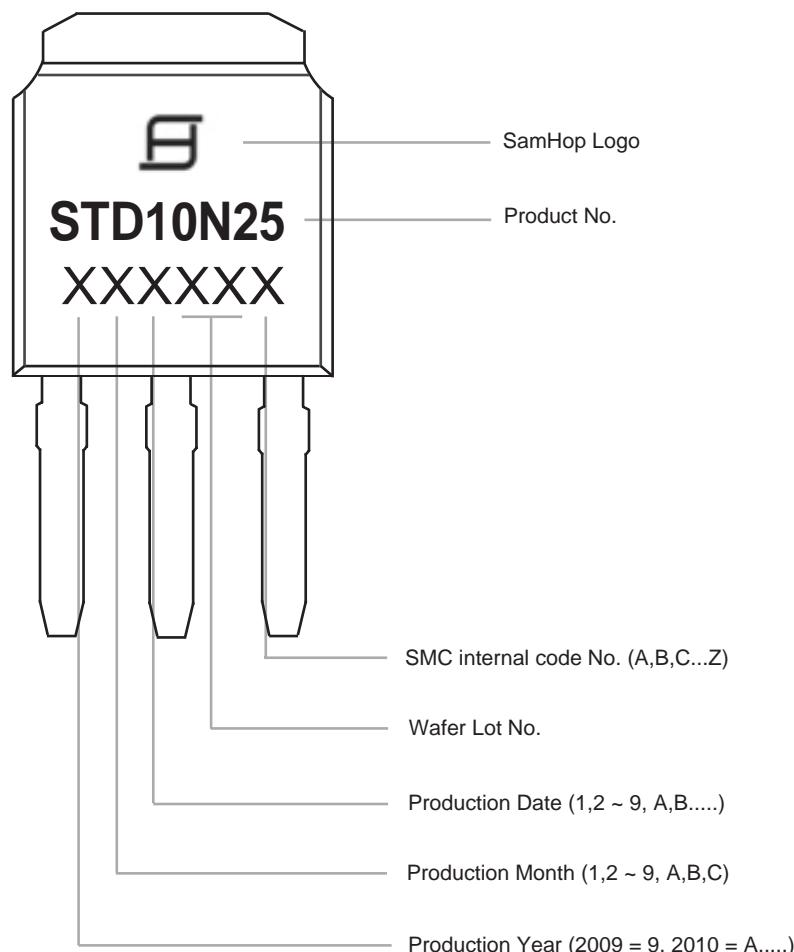
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